2017 A

[illegible]

2009 2016

1,109 4,335.5

21.50%

2016

1,644.3 24.1%

2016

25.1% 1,126.9 1,564.3 13%

2017 1-6 2,201.3 19.1%

21.1% 830.1 25.6%

571.2 800.1 13.2%

IC

2

CSP WLP TSV

2025 3D

3

40% 2010

6% 2014 10%

2012 1,000

2016 1,564.3

FC/QFN BGA

LGA

3D-TSV

2

1

Fan-out eWLB WLCSP SiP BUMP PoP

2017 9 30

2,681 1,740

FBGA PBGA P-SiP IC

QFN FC-BGA

2

MEMS

FBGA

3

IC

3

173,492 169,498 3,994

4

24,181

7.52 10.74%

5

78

6

[2017]69

201732028100415

1

Bumping WLCSP

82 Bumping 47

3

2

1

2003

6

3202851600839

[2016]71

1

108,000

2

1

2014 2015 2016 2017 9

63.12% 73.83% 77.55% 70.12%

2015

2017 9 30 2016 12 31 2015 12 31 2014

12 31

		2017 **9 30**	**2016** **12 31**	**2015** **12 31**	**2014** **12 31**
002185.SZ		33.49%	28.29%	25.22%	39.28%
002156.SZ		46.94%	45.18%	42.56%	40.22%
603005.SH		15.13%	13.47%	17.55%	23.25%
		31.85%	**28.98%**	**28.44%**	**34.25%**
600584.SH		**70.12%**	**77.55%**	**73.83%**	**63.12%**

2017